

**What is claimed is:**

1. An electronic apparatus, comprising:

a semiconductor element installed within a housing;

a heat-receiving portion for receiving heat generated from  
5 said semiconductor element; and

a heat radiation portion being connected between said heat  
radiation portion and said heat-receiving portion through conduits,  
wherein a heat diffusion plate is provided between said  
heat-receiving portion and said semiconductor element.

10 2. The electronic apparatus, as described in the claim 1,  
wherein:

said heat diffusion plate is made of a metal defining a  
hermetically closed space therein, for enclosing evaporation  
medium within an inside thereof.

15 3. The electronic apparatus, as described in the claim 2,  
wherein:

within the inside of said hermetically close space is  
attached a metal plate, expanding radial directions from a portion  
of said semiconductor element.

20 4. The electronic apparatus, as described in the claim 3,  
wherein:

said metal plate is formed zigzagging.

5. The electronic apparatus, as described in the claim 1,  
wherein:

25 said heat-receiving portion comprises four (4) pieces of  
liquid circulation flow passages within an inside thereof.

6. The electronic apparatus, as described in the claim 1,

wherein:

said liquid circulation flow passages are defined by three (3) pieces of partition walls attached on an interior wall surface of an upper cover for building up said heat-receiving portion.